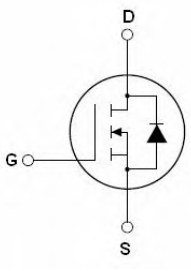
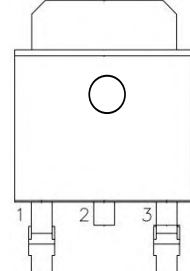
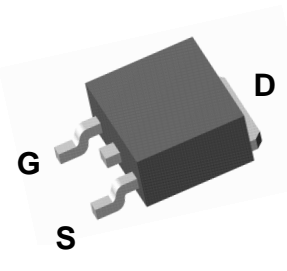


FH2045D

N-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The FH2045D uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.</p> <p>Application</p> <ul style="list-style-type: none"> ● Load switching ● Hard switched and high frequency circuits ● Uninterruptible power supply 	<p>General Features</p> <ul style="list-style-type: none"> ● $V_{DS}=20V, I_D=80A$ ● $R_{DS(ON)} = 3.2 m\Omega$ (Typ) @ $V_{GS}=4.5V$ ● $R_{DS(ON)} = 4.0 m\Omega$ (Typ) @ $V_{GS}=2.5V$ ● High density cell design for ultra low R_{Dson} ● Fully characterized avalanche voltage and current ● Good stability ● Excellent package for good heat dissipation
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TO-252

Schematic diagram

Marking and pin assignment

TO-252 top view

Absolute Maximum Ratings @ $T_j=25^{\circ}C$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D @ T_A=25^{\circ}C$	Drain Current, V_{GS} @ 4.5V ³	80	A
$I_D @ T_A=70^{\circ}C$	Drain Current, V_{GS} @ 4.5V ³	65	A
I_{DM}	Pulsed Drain Current ¹	160	A
$P_D @ T_A=25^{\circ}C$	Total Power Dissipation	3.13	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$

Thermal Data

Symbol	Parameter	Value	Unit
R_{thj-c}	Maximum Thermal Resistance, Junction-case	5	$^{\circ}C/W$
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	40	$^{\circ}C/W$

Electrical Characteristics @ $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=4.5V, I_D=20A$	-	3.2	4.5	$m\Omega$
		$V_{GS}=2.5V, I_D=12A$	-	4.0	6.0	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=1mA$	0.6	-	0.9	V
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=20A$	-	130	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=16V, V_{GS}=0V$	-	-	10	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
Q_g	Total Gate Charge	$I_D=20A$	-	62	99.2	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=10V$	-	4	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=4.5V$	-	21	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=10V$	-	12	-	ns
t_r	Rise Time	$I_D=1A$	-	20	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega$	-	100	-	ns
t_f	Fall Time	$V_{GS}=5V$	-	80	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	4000	6400	pF
C_{oss}	Output Capacitance	$V_{DS}=10V$	-	780	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0MHz$	-	625	-	pF
R_g	Gate Resistance	$f=1.0MHz$	-	1.4	2.8	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_S=2.5A, V_{GS}=0V$	-	-	1.2	V
t_{rr}	Reverse Recovery Time	$I_S=20A, V_{GS}=0V,$	-	43	-	ns
Q_{rr}	Reverse Recovery Charge	$di/dt=100A/\mu s$	-	26	-	nC

Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse test
3. Surface mounted on 1 in² 2oz copper pad of FR4 board, $t \leq 10\text{sec}$; 135°C/W when mounted on min. copper pad.
4. Maximum current limited by package.

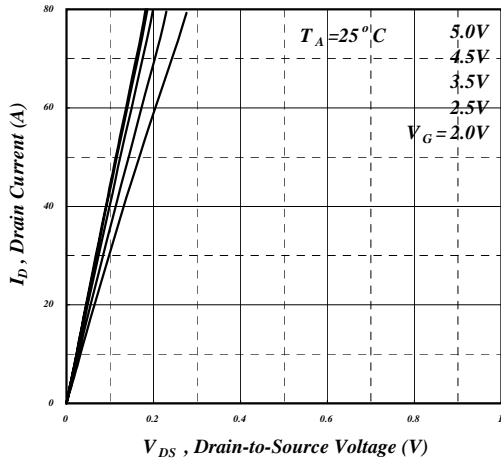


Fig 1. Typical Output Characteristics

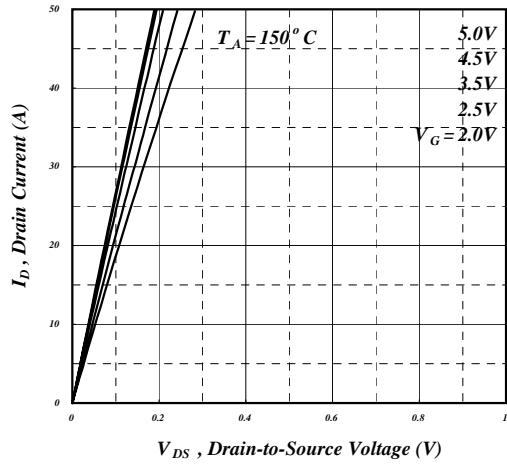


Fig 2. Typical Output Characteristics

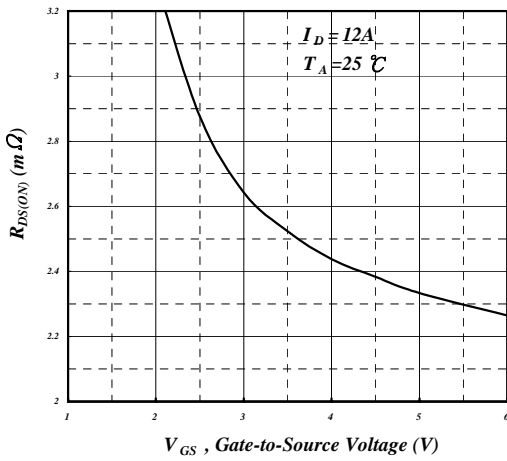


Fig 3. On-Resistance v.s. Gate Voltage

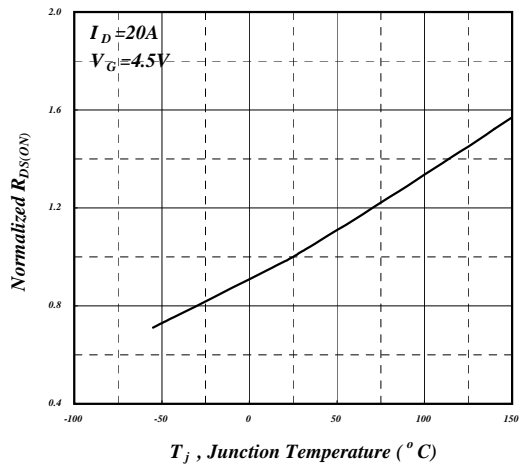


Fig 4. Normalized On-Resistance v.s. Junction Temperature

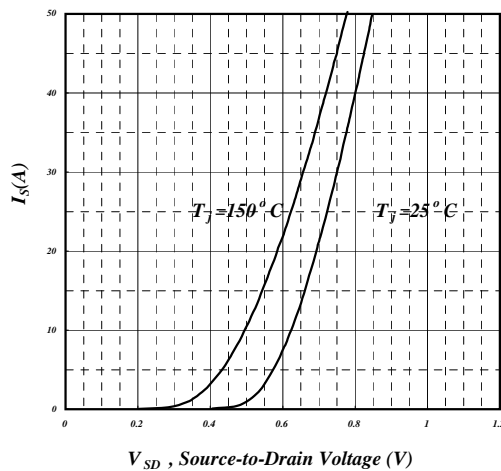


Fig 5. Forward Characteristic of Reverse Diode

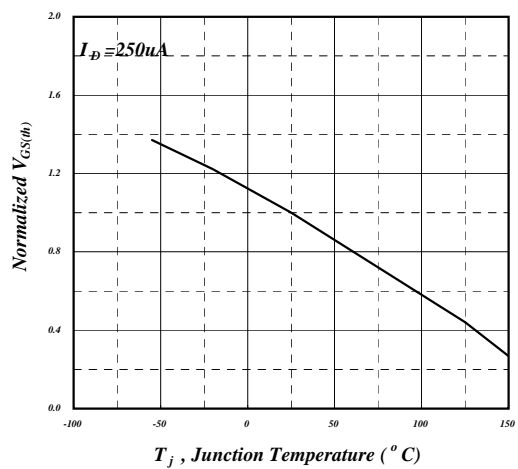


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

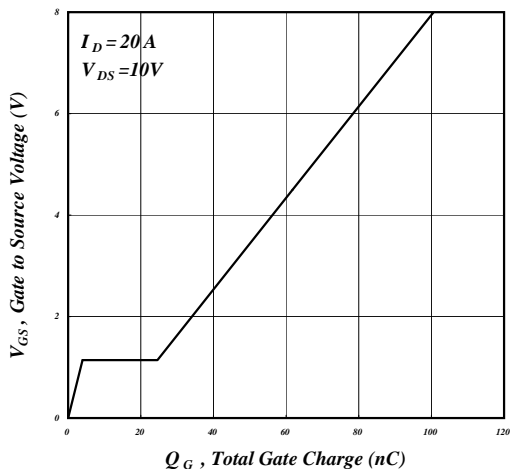


Fig 7. Gate Charge Characteristics

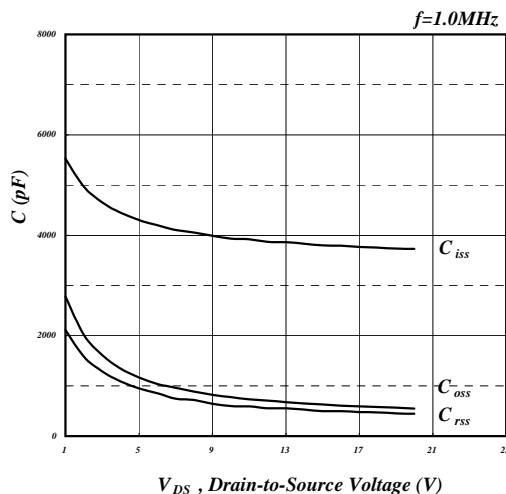


Fig 8. Typical Capacitance Characteristics

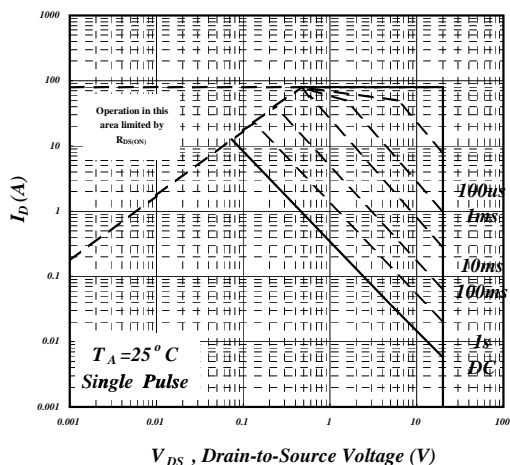


Fig 9. Maximum Safe Operating Area

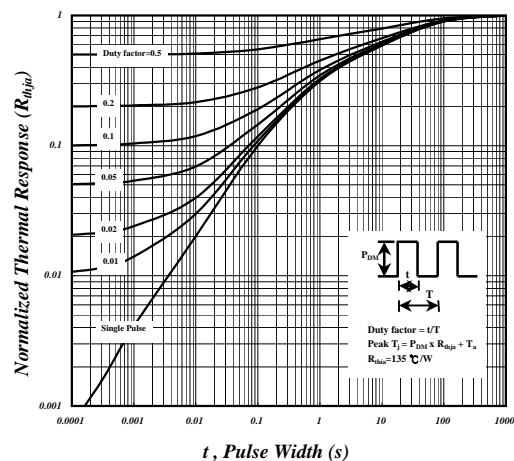


Fig 10. Effective Transient Thermal Impedance

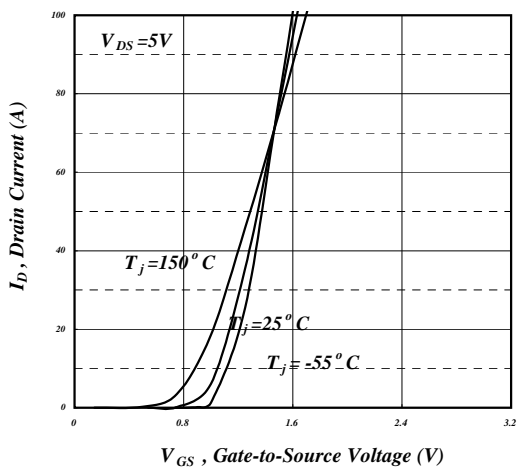


Fig 11. Transfer Characteristics

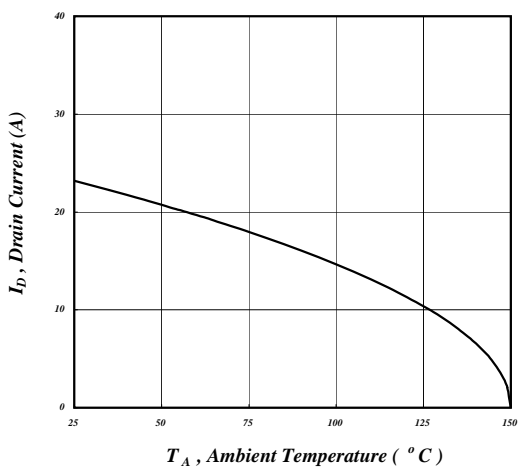


Fig 12. Drain Current v.s. Ambient Temperature

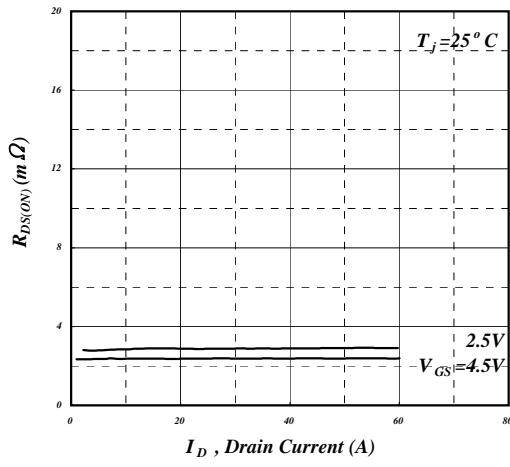


Fig 13. Typ. Drain-Source on State Resistance

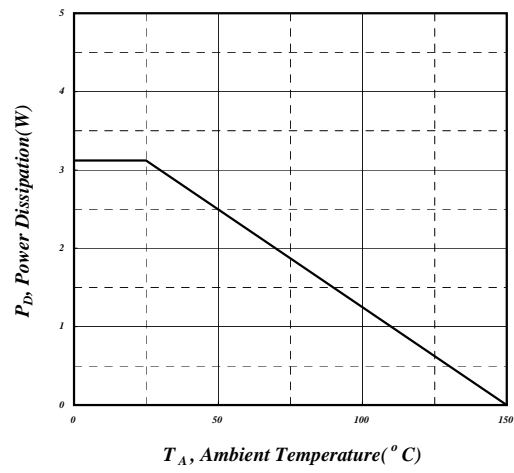
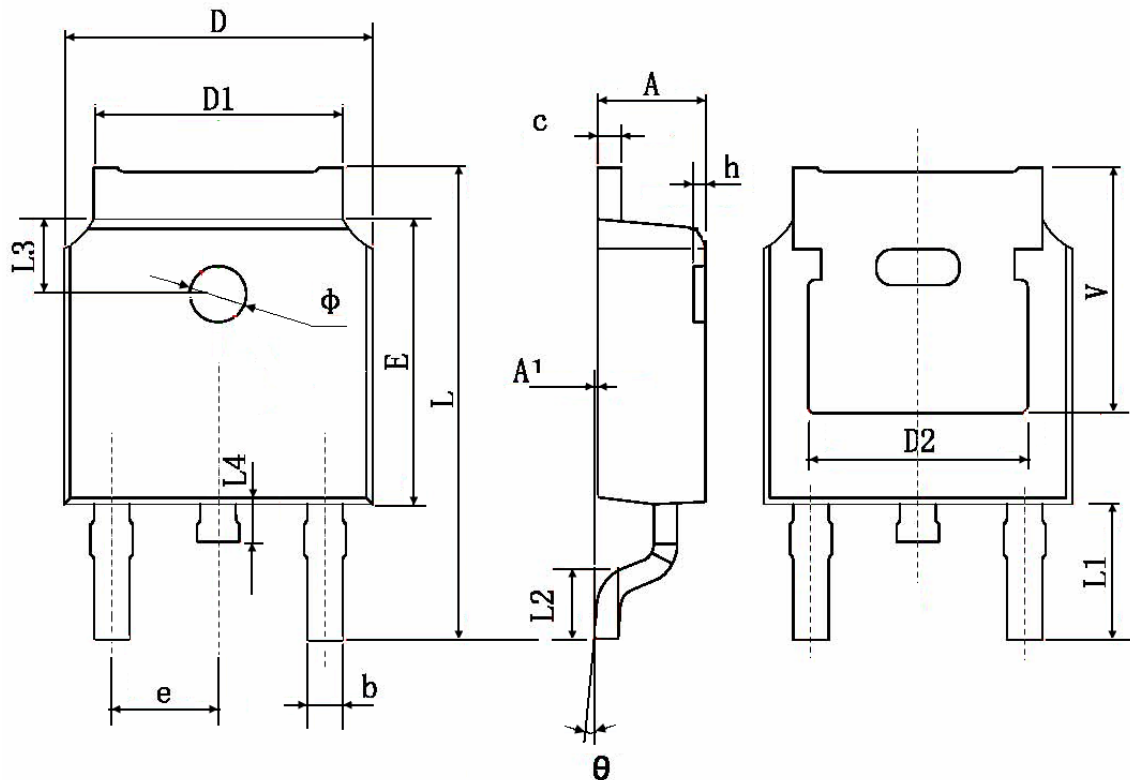


Fig 14. Total Power Dissipation

TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	